

Electronic Patent Application Fee Transmittal

Application Number:	10593137			
Filing Date:	18-Sep-2006			
Title of Invention:	RESIN COMPOSITION AND SEMICONDUCTOR DEVICE PRODUCED BY USING THE SAME			
First Named Inventor/Applicant Name:	Hikaru Okubo			
Filer:	Michael A. Makuch/Cynthia Johnson			
Attorney Docket Number:	033036.110			
Filed as Large Entity				
U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appl issue fee	1501	1	1740	1740
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
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Total in USD (\$)				2040